

HD74LS374

Octal D-type Edge-triggered Flip-Flops (with three-state outputs)

REJ03D0483-0200

Rev.2.00

Feb.18.2005

The HD74LS374, 8-bit register features totem-pole three-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. The high-impedance third state and increased high-logic-level drive provide this register with the capability of being connected directly to and driving the bus lines in a bus-organized system without need for interface or pull-up components. They are particularly attractive for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The eight flip-flops are edge-triggered D-type flip-flops. On the positive transition the clock, the Q outputs will be set to the logic states that were setup at the D inputs.

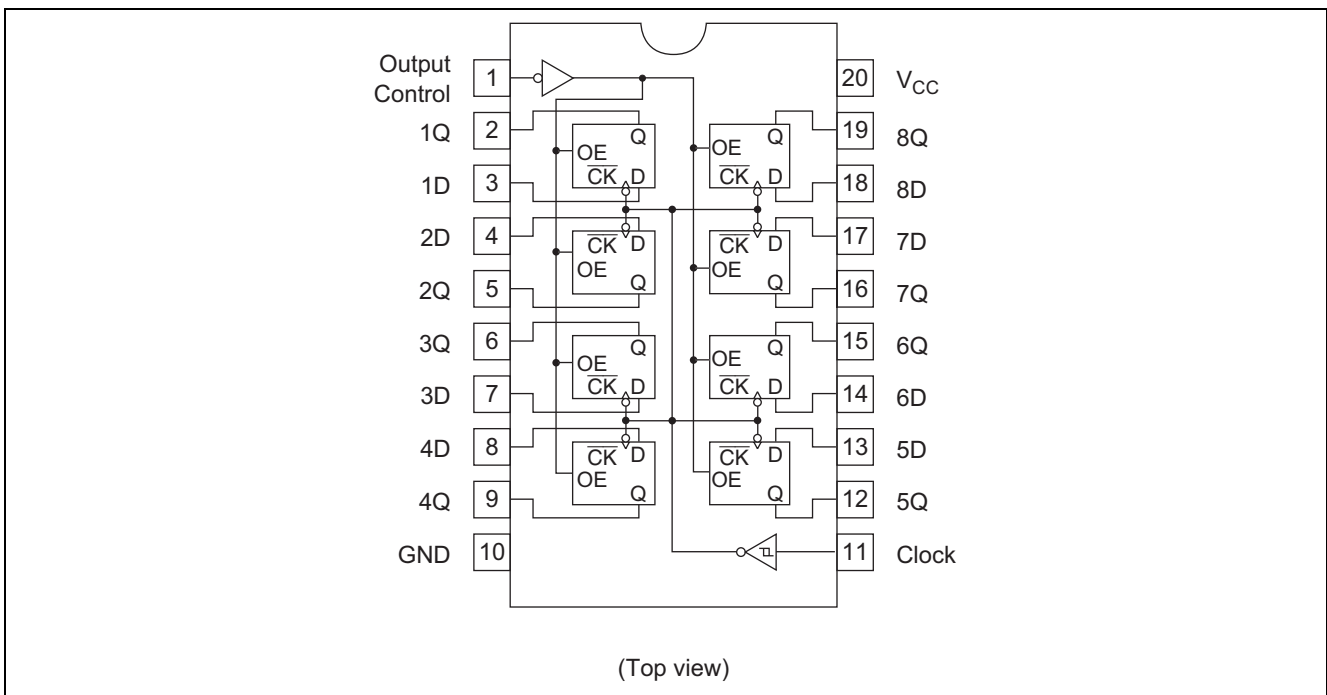
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS374P	DILP-20 pin	PRDP0020AC-B (DP-20NEV)	P	—
HD74LS374FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)
HD74LS374RPEL	SOP-20 pin (JEDEC)	PRSP0020DC-A (FP-20DBV)	RP	EL (1,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement

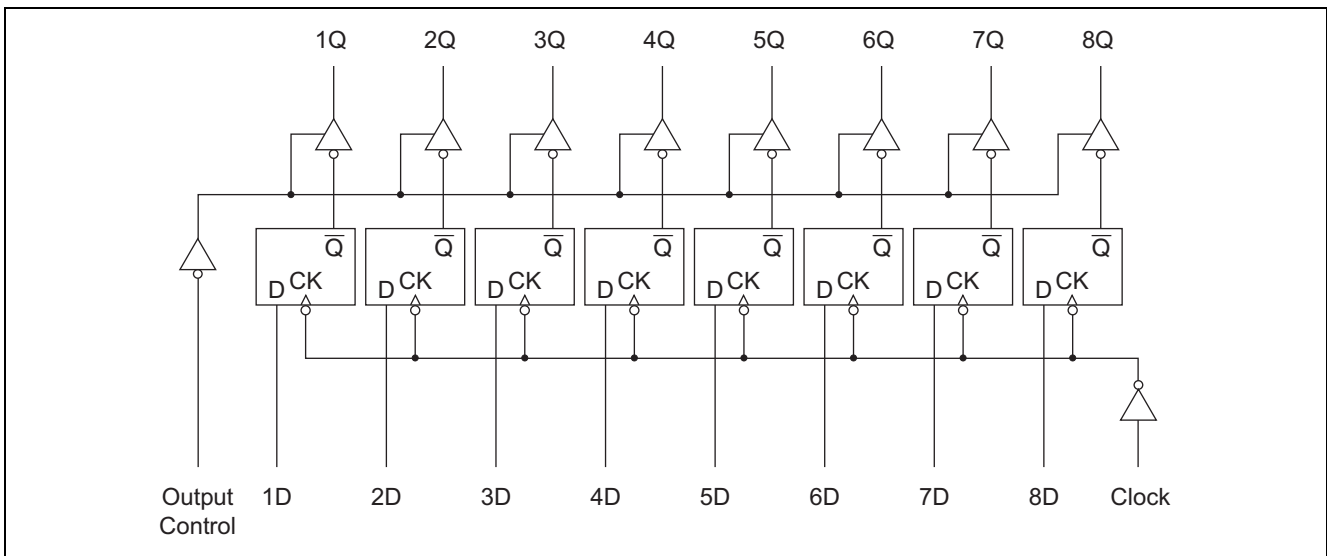


Function Table

Inputs		Outputs
Output control	Clock	Q
L	↑	H
L	↑	L
L	L	Q ₀
H	X	Z

Notes: H; high level, L; low level, X; irrelevant
 ↑; transition from low to high level
 Q₀; level of Q before the indicated steady state input conditions were established
 Z; off (high-impedance) state of a three state output

Block Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V _{CC}	7	V
Input voltage	V _{IN}	7	V
Power dissipation	P _T	400	mW
Storage temperature	T _{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V _{CC}	4.75	5.00	5.25	V
Output voltage	V _{OH}	—	—	5.5	V
Output current	I _{OH}	—	—	-2.6	mA
	I _{OL}	—	—	24	mA
Operating temperature	T _{opr}	-20	25	75	°C
Clock pulse width	t _w	"H" Level	15	—	ns
		"L" Level	15	—	ns
Data setup time	t _{su}	20↑	—	—	ns
Data hold time	t _h	0↑	—	—	ns

Electrical Characteristics

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V _{IH}	2.0	—	—	V	
	V _{IL}	—	—	0.8	V	
Output voltage	V _{OH}	2.4	—	—	V	V _{CC} = 4.75 V, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -2.6 mA
	V _{OL}	—	—	0.4	V	I _{OL} = 12 mA
—		—	0.5	I _{OL} = 24 mA		V _{CC} = 4.75 V, V _{IH} = 2 V, V _{IL} = 0.8 V
Output current	I _{OZH}	—	—	20	μA	V _O = 2.7 V
	I _{OZL}	—	—	-20		V _O = 0.4 V
Input current	I _{IH}	—	—	20	μA	V _{CC} = 5.25 V, V _I = 2.7 V
	I _{IL}	—	—	-0.4	mA	V _{CC} = 5.25 V, V _I = 0.4 V
	I _I	—	—	0.1	mA	V _{CC} = 5.25 V, V _I = 7 V
Short-circuit output current	I _{OS}	-30	—	-130	mA	V _{CC} = 5.25 V
Supply current	I _{CC}	—	27	40	mA	V _{CC} = 5.25 V, V _I = 4.5 V (Output control)
Input clamp voltage	V _{IK}	—	—	-1.5	V	V _{CC} = 4.75 V, I _{IN} = -18 mA

Note: * V_{CC} = 5 V, Ta = 25°C

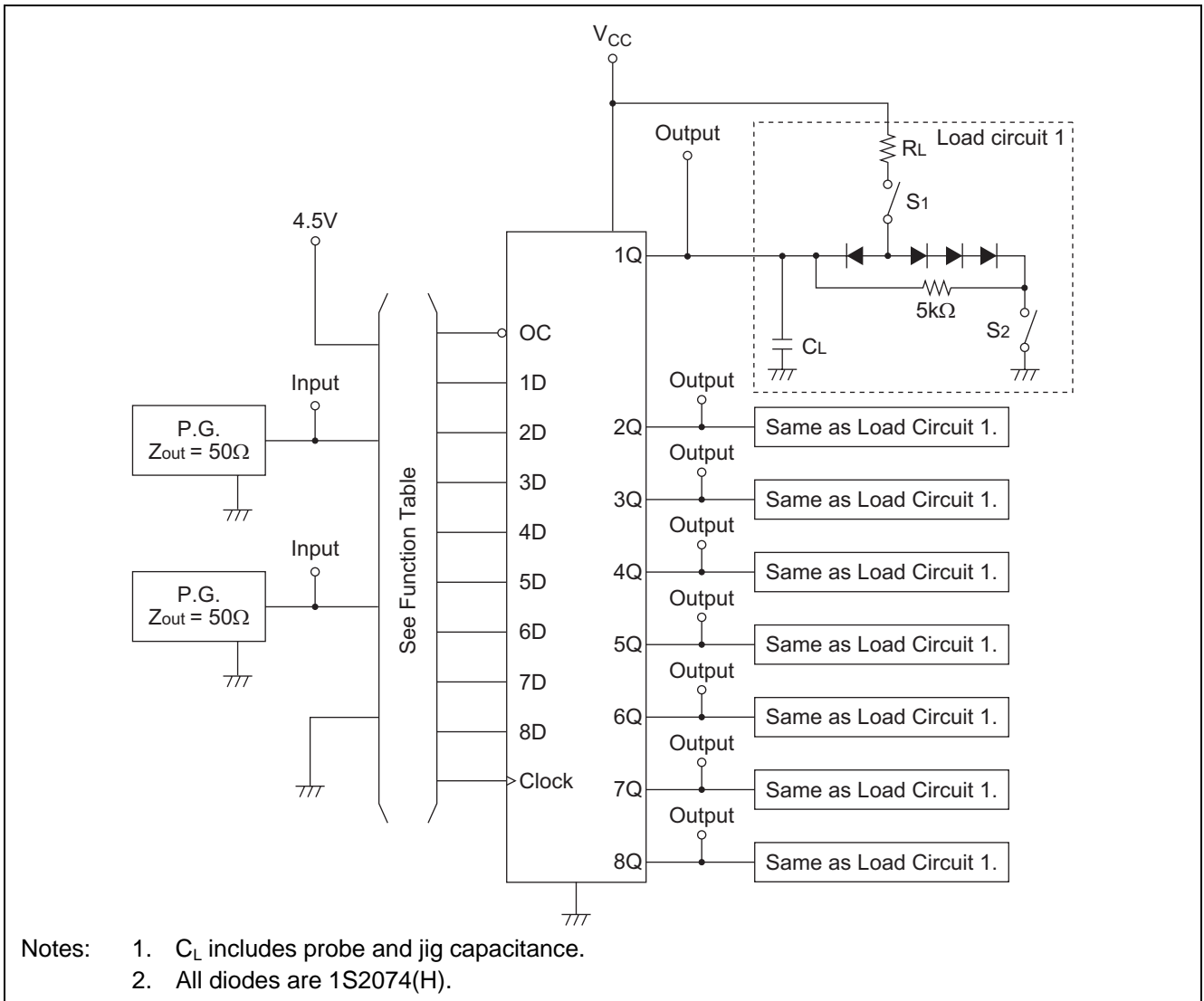
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

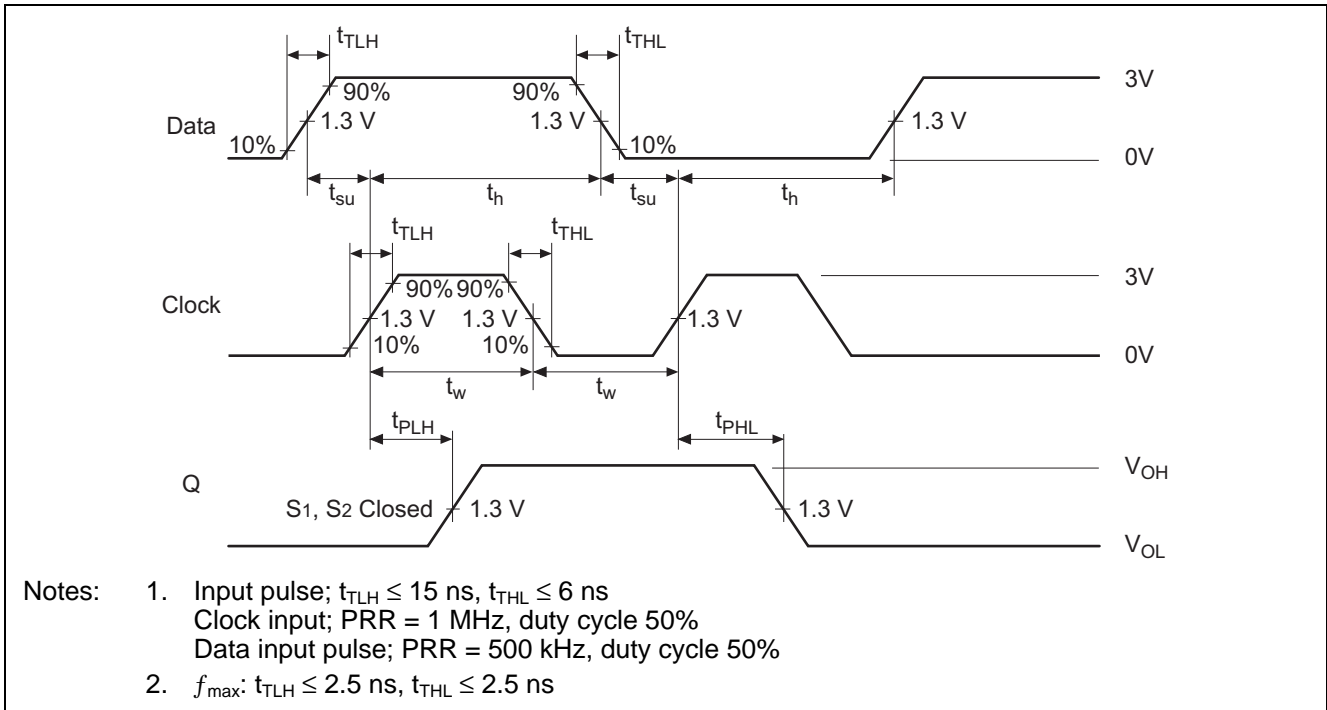
Item	Symbol	Inputs	Output	min.	typ.	max.	Unit	Condition
Maximum clock frequency	f _{max}	Clock	Q	35	50	—	MHz	C _L = 45 pF, R _L = 667 Ω
Propagation delay time	t _{PLH}	Clock	Q	—	15	28	ns	
	t _{PHL}			—	19	28		
Output enable time	t _{ZH}	OC	Q	—	20	28		
	t _{ZL}			—	21	28		
Output disable time	t _{HZ}	OC	Q	—	12	20		C _L = 5 pF, R _L = 667 Ω
	t _{LZ}			—	14	25		

Testing Method

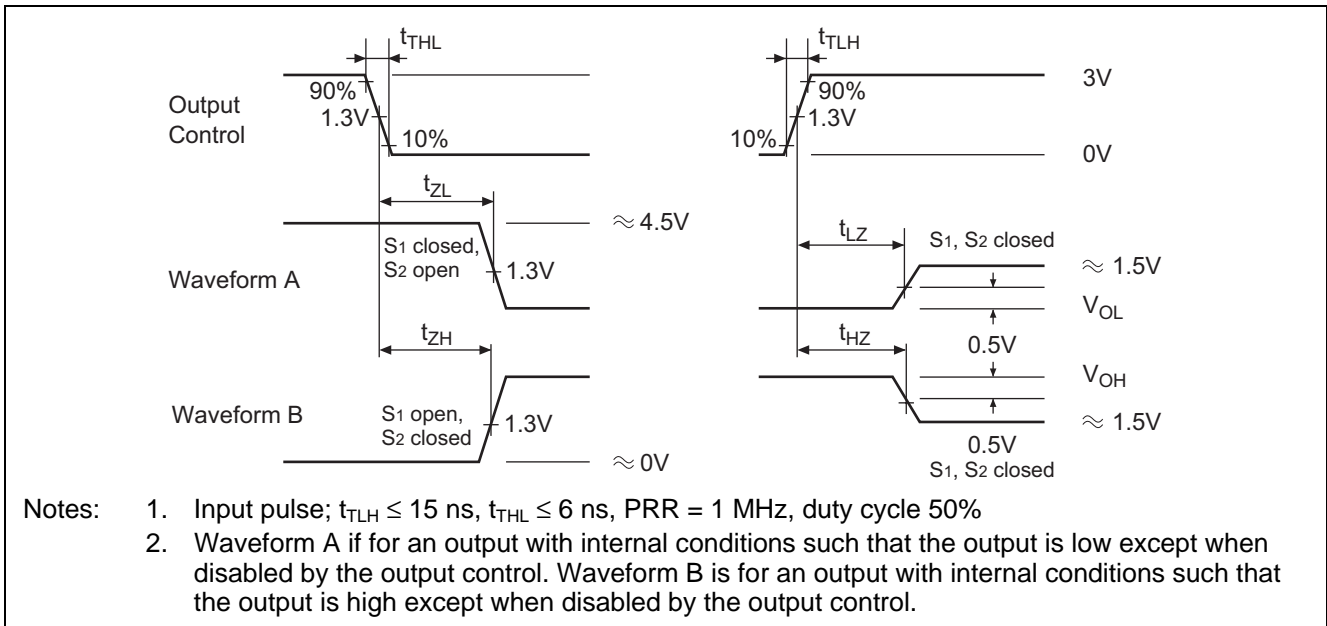
Test Circuit



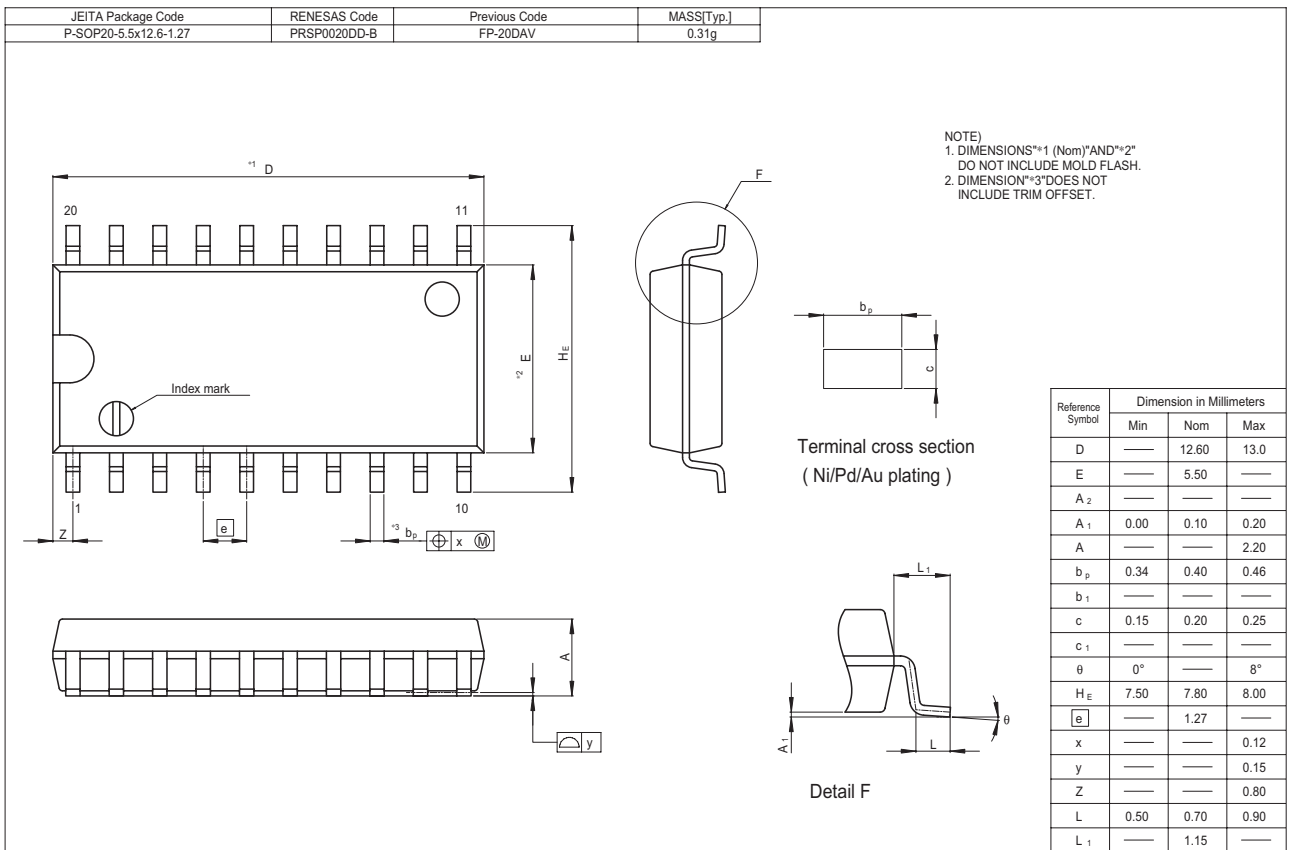
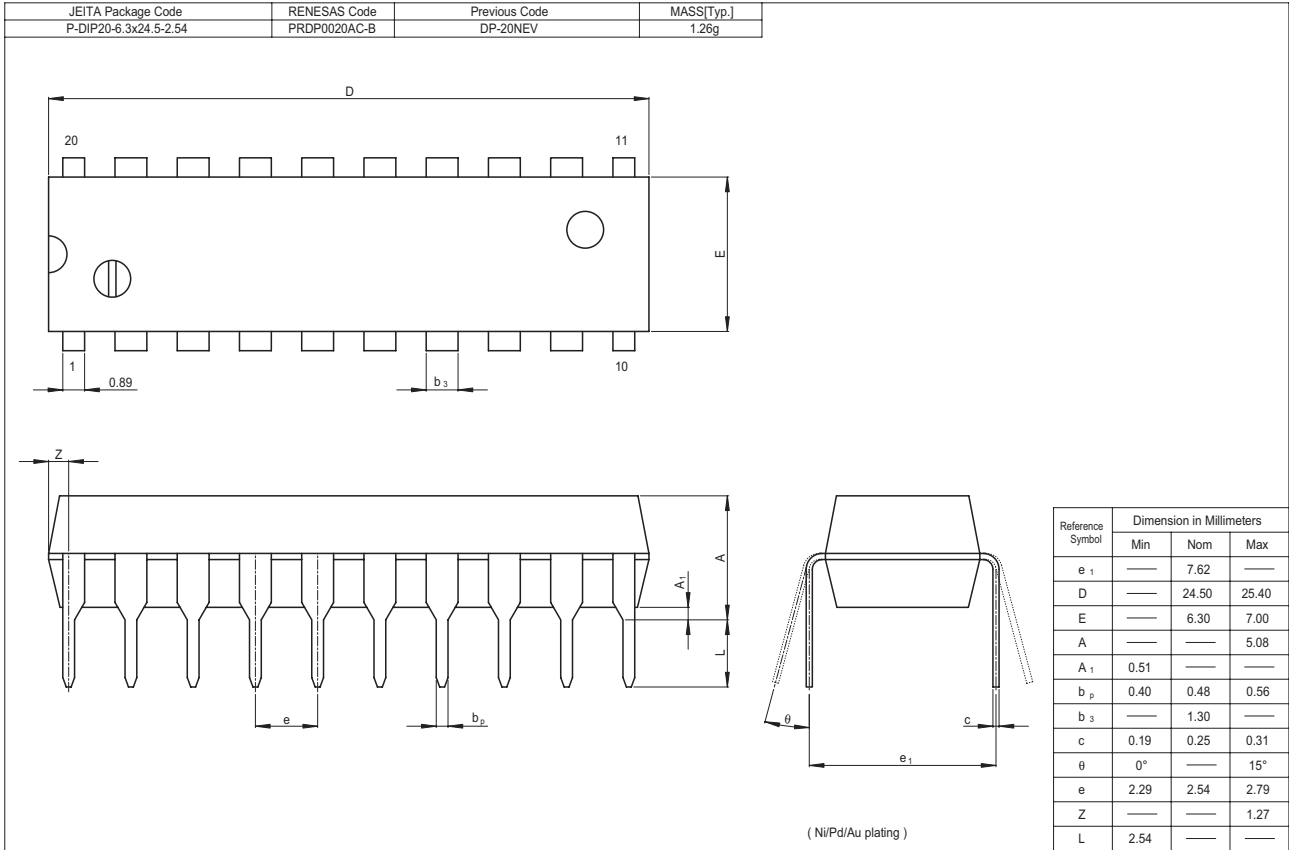
Waveforms 1



Waveforms 2

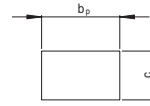
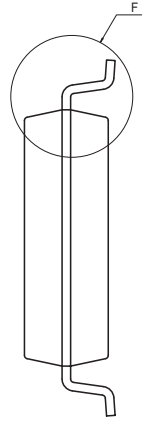
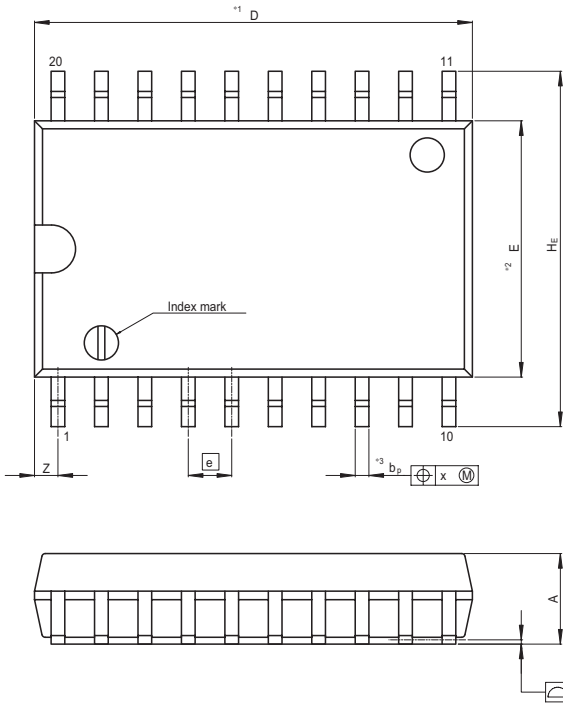


Package Dimensions

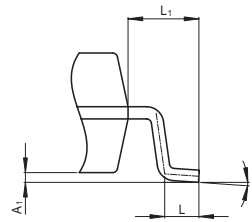


HD74LS374

JEITA Package Code P-SOP20-7.5x12.8-1.27	RENESAS Code PRSP0020DC-A	Previous Code FP-20DBV	MASS[Typ.] 0.52g
---	------------------------------	---------------------------	---------------------



Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS**1 (Nom)**AND**2*
@ DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3*DOES NOT
@ INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.80	13.2
E	—	7.50	—
A ₂	—	—	—
A ₁	0.10	0.20	0.30
A	—	—	2.65
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.20	0.25	0.30
c ₁	—	—	—
θ	0°	—	8°
H _E	10.00	10.40	10.65
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.935
L	0.40	0.70	1.27
L ₁	—	1.45	—

Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs!

1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors.
Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



RENESAS SALES OFFICES

<http://www.renesas.com>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd.

Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001